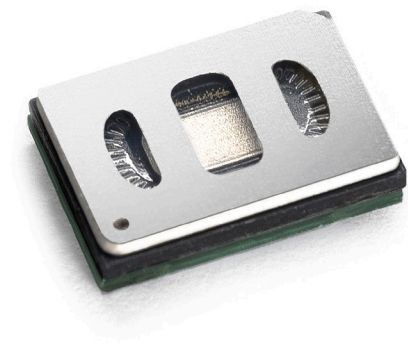


MEMS SPEAKERS

ADAP UT-P2019 | DATASHEET

U))) SOUND



Adap MEMS speakers are ideal for free-field audio solutions such as wearables. Thanks to its small size and low weight, Adap offers maximum flexibility for outstanding design approaches. Providing a wide bandwidth, it enables high-res audio applications. Adap produces tangible, clear and rich sound, immersing the listener into their personal audio environment.

FEATURES

- Enables modern, lightweight and ergonomic designs for sophisticated wearables
- Seamless integration into acoustic devices for everyday use
- Longer battery life due to the speaker's low power consumption
- Enhanced cover for handling protection
- Competitive sound pressure level
- No magnetic field
- Low heat generation

APPLICATIONS

Adap speakers can be used for free-field audio systems as well as wearables. For 2-way earphones Adap speakers are suitable as tweeters.

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REVISION HISTORY

Released in January 2020

June 2020: Update in power consumption section

SPECIFICATIONS

General acoustics			
$f_{res} @ 15 V_p$	[kHz]	2.9	±15%
$Q @ f_{res} / 15 V_p$	[-]	0.7	
Effective membrane surface – S_D	[mm ²]	12	
Equivalent volume – V_{AS}	[mm ³]	40	
Front volume inside speaker	[mm ³]	5.6	
Back volume inside speaker	[mm ³]	20	
Acoustics in baffle (IEC 60268-5)			
SPL @ 1 kHz / 15 V_p	[dB]	51	±3.0
SPL @ 4 kHz / 15 V_p	[dB]	71	±3.0
SPL @ 10 kHz / 15 V_p	[dB]	74	±3.0
SPL @ 1 kHz / 5 V_p	[dB]	40	±3.0
SPL @ 4 kHz / 5 V_p	[dB]	60	±3.0
SPL @ 10 kHz / 5 V_p	[dB]	63	±3.0
THD @ 1 kHz / 5 V_p	[%]	13	+20
THD @ 4 kHz / 5 V_p	[%]	4	+3
THD @ 10 kHz / 5 V_p	[%]	4	+3
Electronics			
Capacity @ 1 kHz / 15 V_p	[nF]	38	±20%
Operating conditions			
Maximum AC voltage (peak) – up to 40 kHz	[V_p]	15	
Maximum DC voltage	[V]	15	
Maximum AC current (peak)	[mA _p]	200	
Power consumption			
with IEC noise (60268-1) @ 60 dB	[mW]	46	

*Power consumption test conditions can be found in page 6.

MECHANICAL DIMENSIONS

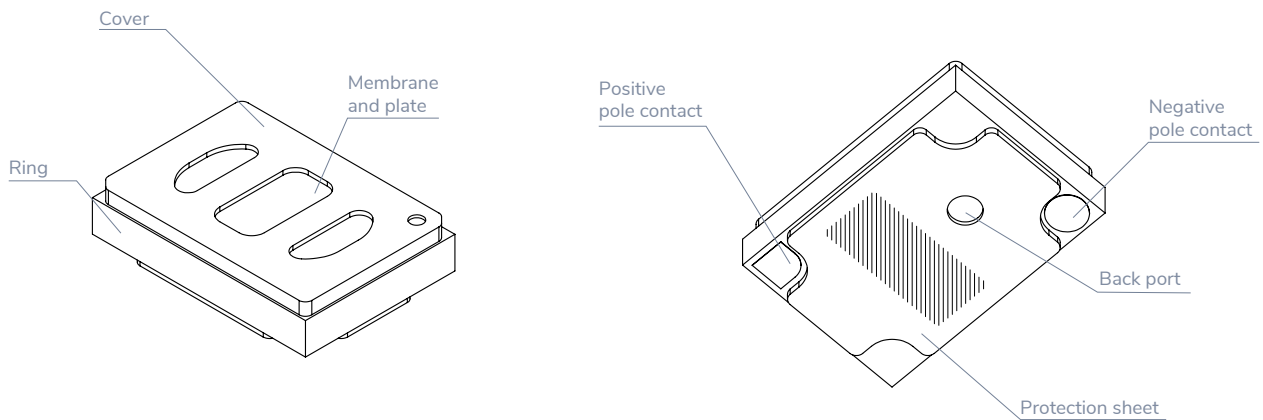


Figure 1: Mechanical drawings: perspective view

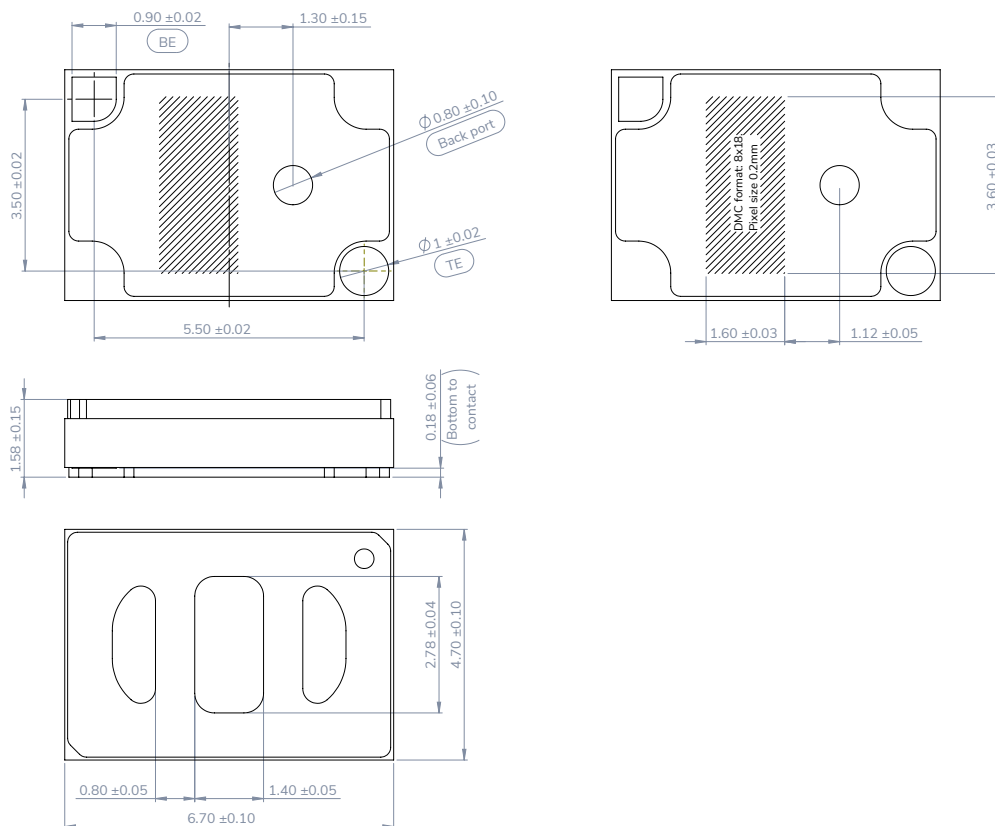


Figure 2: Mechanical drawings: top/down/side view

Mechanics		
Size	[mm]	6.7 x 4.7 x 1.58
Total speaker weight	[mg]	80
Total speaker cubic volume	[mm ³]	50

FORCE ON SPEAKER

Type of stress	Maximum handling force [N]	Maximum permanent force [N]
Front face compression	20	13
Side face compression	20	13
3 point bending	10	5
Force on membrane	0	0

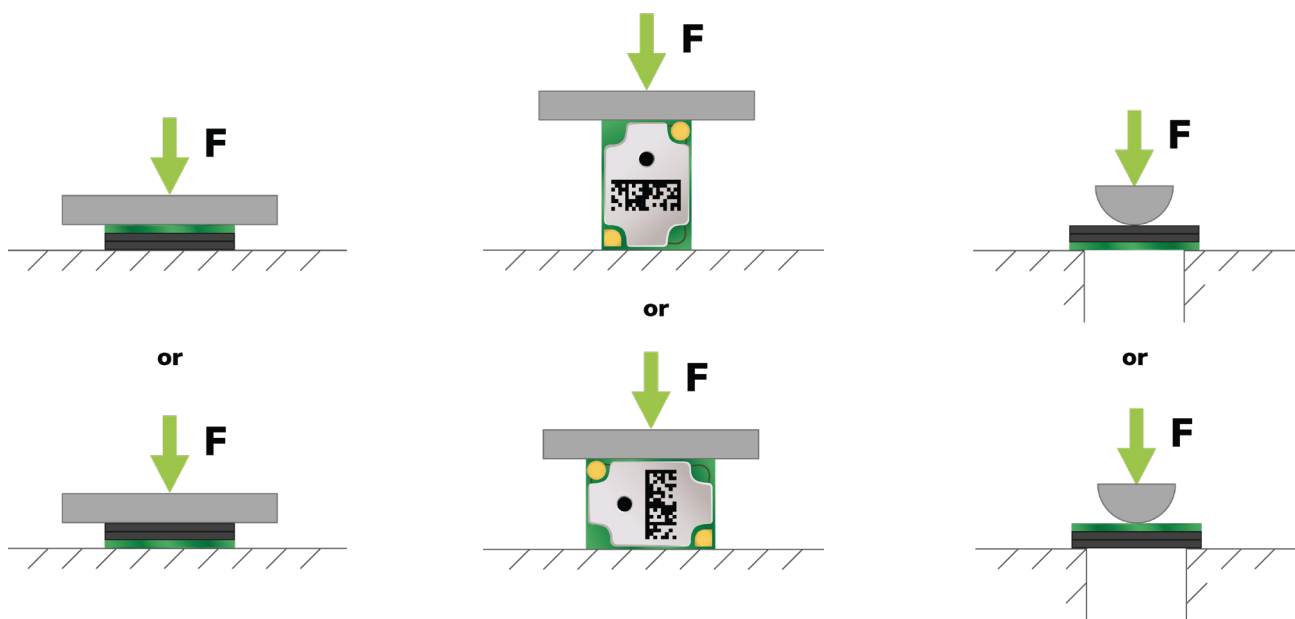


Figure 3: Left: front face compression, centre: side face compression, right: 3-point bending

TEST CONDITIONS

ACOUSTICS

General	
Measurement system	Audio Precision APx
Measurement signal	Exp. Sweep
Voltage levels – audio $V_{DC} + V_{AC}$	15 V + 15 V _p
Applied back volume	Open (infinite)

Baffle	
Baffle type	IEC 60268-5
Mic distance	3 cm
Reference distance	10 cm
Microphone	GRAS 46AC
Microphone diameter	1/2"

BAFFLE MEASUREMENT ADAPTER

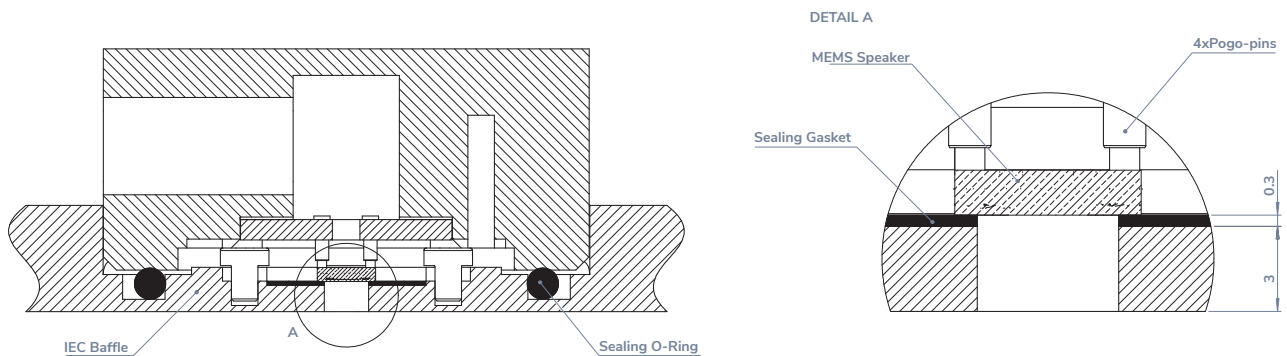


Figure 4: The outlet through the baffle for the speaker has the same shape as the inside of the speaker cover

POWER CONSUMPTION AND REFERENCE DRIVING CIRCUIT

Power consumption is measured with one Adap MEMS speaker, including the typical driving circuitry with the DC boost converter TPS61046 and the amplifier TI LM4858. The main blocks are presented in Figure 2 and Figure 3.

Condition: Supply voltage 3.6 V; speaker placed in baffle; all noise signals with high pass filter 2nd order @ 2 kHz.

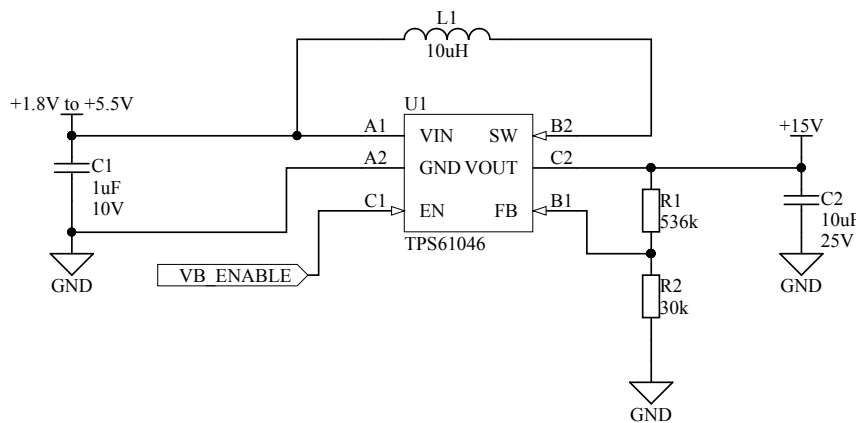


Figure 5: TPS61046 boost converter including needed passive components

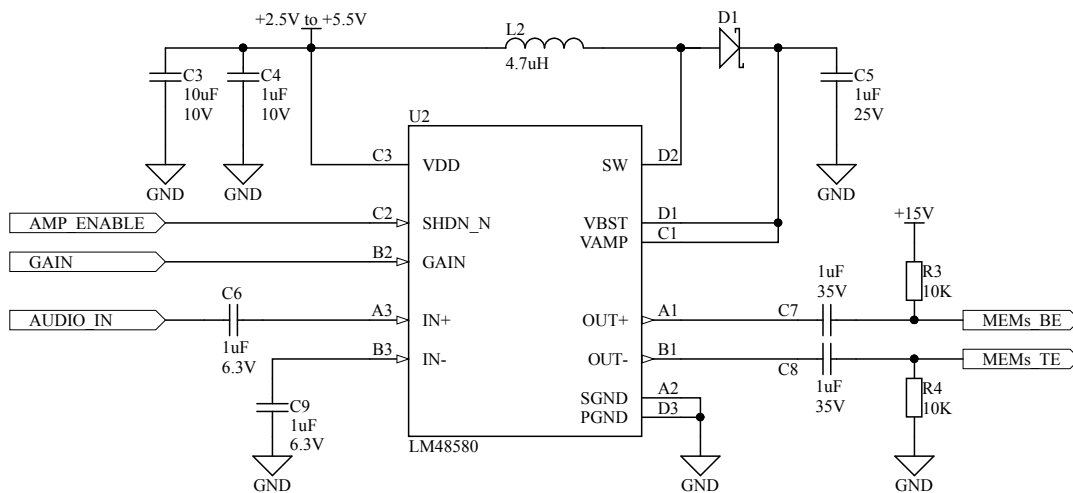


Figure 6: LM48580 amplifier, including needed passive components

The boost converter is configured to provide a constant 15 V_{DC} offset for the amplifier. The amplifier circuit itself is based on the typical application diagram from the LM48580 datasheet. It is based on a single-ended input signal but can also be modified according to the datasheet to a differential input.

ACOUSTIC PERFORMANCE

ACOUSTIC PERFORMANCE IN BAFFLE (IEC 60268-5)

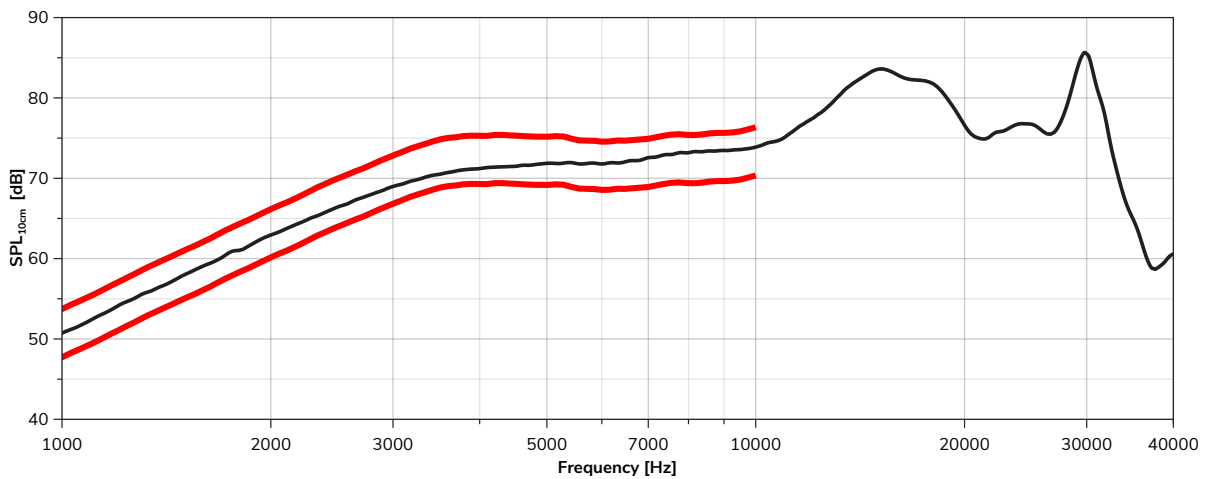


Figure 7: SPL @ 15 V_p drive*

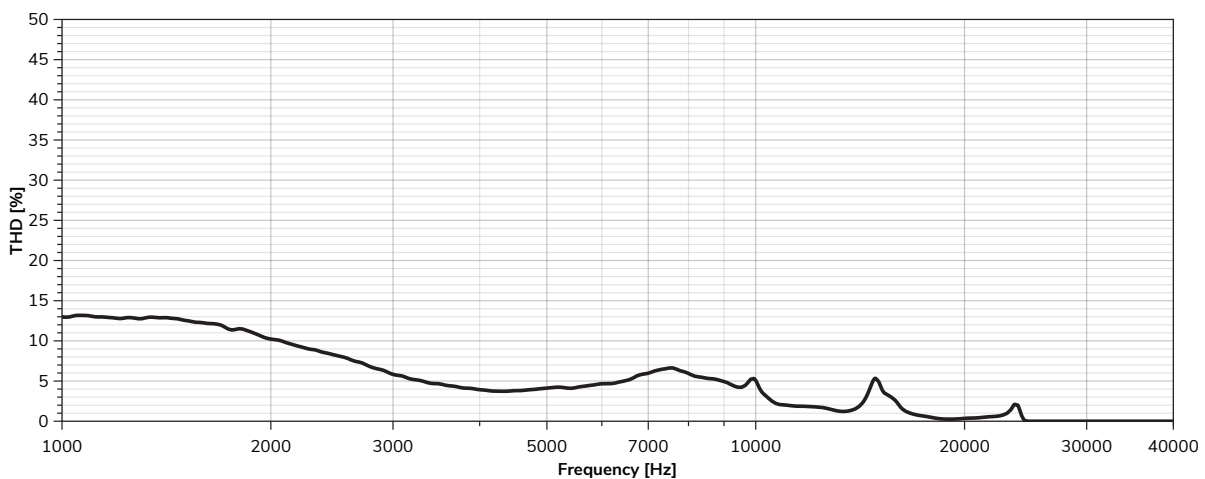


Figure 8: THD 60 dB SPL @ 4 kHz, corresponds to 5 V_p

Red lines in figure 7 indicate the limits. Test limits are used to establish incoming inspection acceptance/rejection criteria, correlation of test equipment with USound is also a requirement for elimination of equipment and test method variation.*

GROUP DELAY

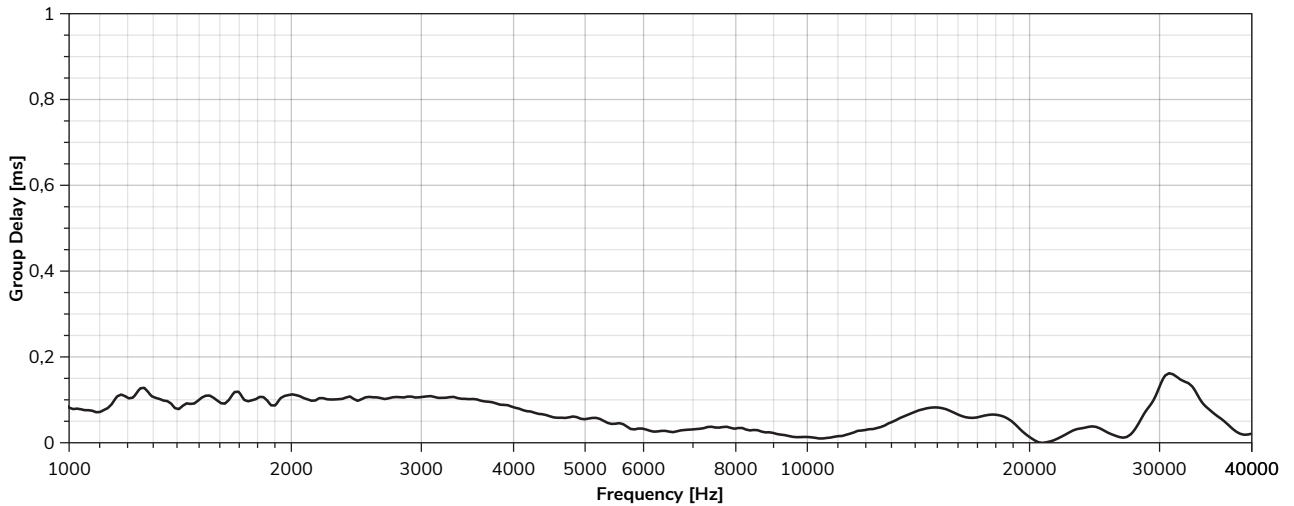


Figure 9: Sampling frequency 96 kHz.
Time delay between speaker and microphone compensated.

IMPULSE RESPONSE

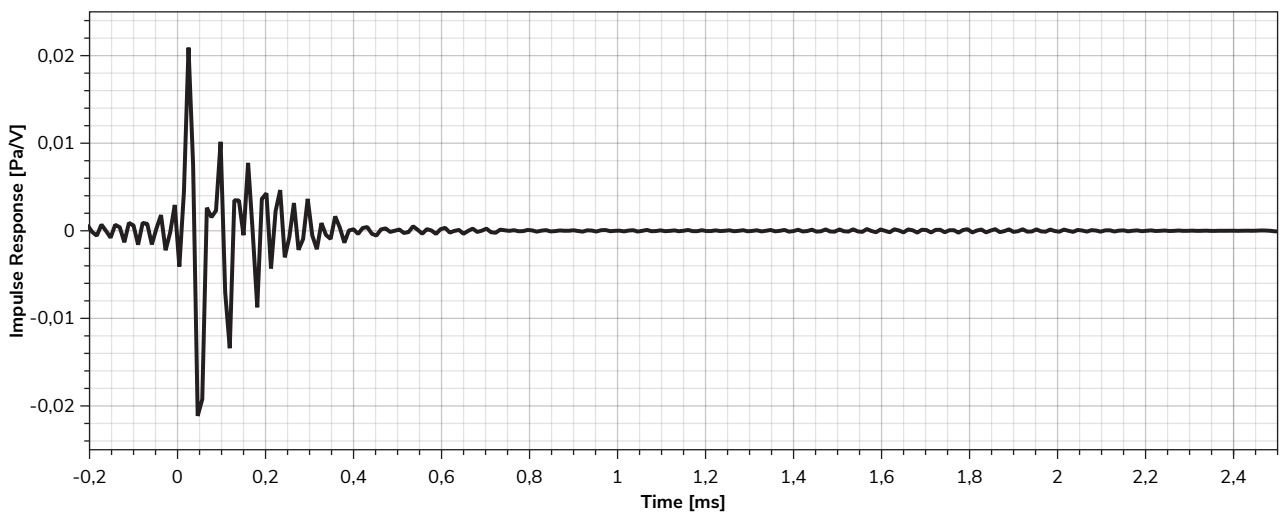


Figure 10: Sampling frequency 96 kHz.
Time delay between speaker and microphone compensated.

ACOUSTIC PERFORMANCE USING THE CARME TEST BOX IN FREE FIELD

To analyse the performance of the Adap MEMS speakers, the Carme test box is available. With a back volume of 100 mm³, Carme provides the necessary sealing to avoid an acoustic short circuit and offers a convenient way to connect Adap to USound's linear amplifier, Amalthea.

To set up the Carme test box, unscrew and separate the PCB from the shell. Remove the housing gasket and place the MEMS speaker with the contact side up. Place the PCB by taking care to match the orientation marks with those on the speaker. Tighten the screws for proper sealing. Using the Carme test box, Adap MEMS speakers can be measured in free field.



Figure 11: Positive input (+) blue and negative input (-) green. The colour coding matches the outputs of Amalthea

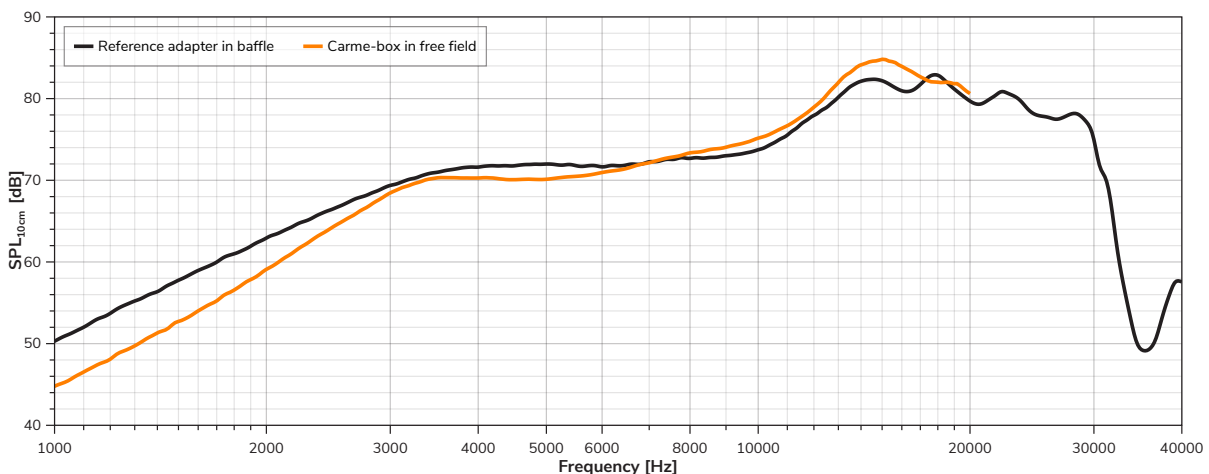


Figure 12: Adap SPL measurement in the Carme test box (10 cm) in free field

HANDLING

GENERAL

It needs to be considered that MEMS devices consist of silicon structures, and therefore, they should be handled with care. Any bending of the MEMS speakers must be avoided while handling, during the assembly process and when permanently inside an application, otherwise the speaker can be damaged.

TWEEZERS

It is recommended to grab the speakers from the sides with blunt curved tweezers and avoid touching the membrane in any case to preserve its functionality and form. Using sharp tweezers while manipulating the speakers can lead to accidentally piercing the membrane and to a loss of functionality.

The risk to damage the speaker can be further minimized if the speaker is handled with the membrane facing down, as shown in the picture below.

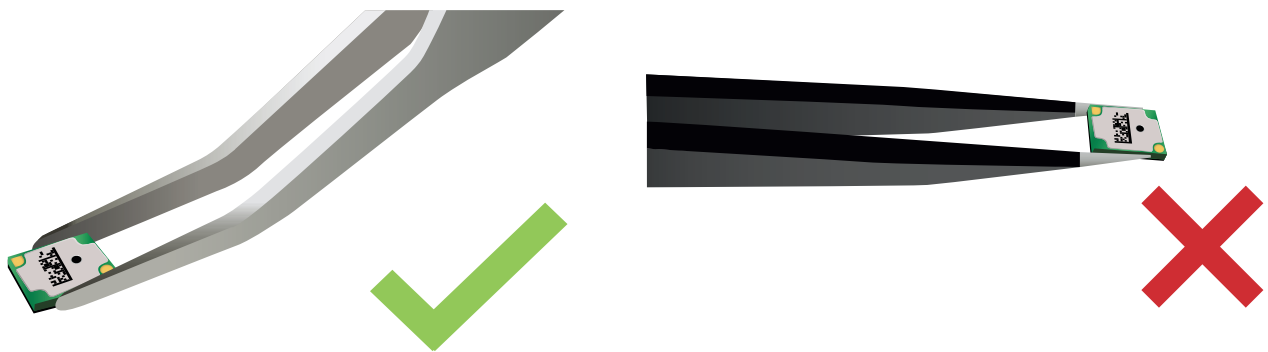


Figure 13: Left: Recommended tweezer type. Right: Not recommended tweezer type

INTEGRATION

It needs to be considered that MEMS devices consist of silicon structures, and therefore, they should be handled with care. Any bending of the MEMS speakers must be avoided while handling, during the assembly process and when permanently inside an application, otherwise the speaker can be damaged.

To avoid bending of the speaker, it's recommended that just the defined contact areas are in touch with the application at front side and back side of the speaker.

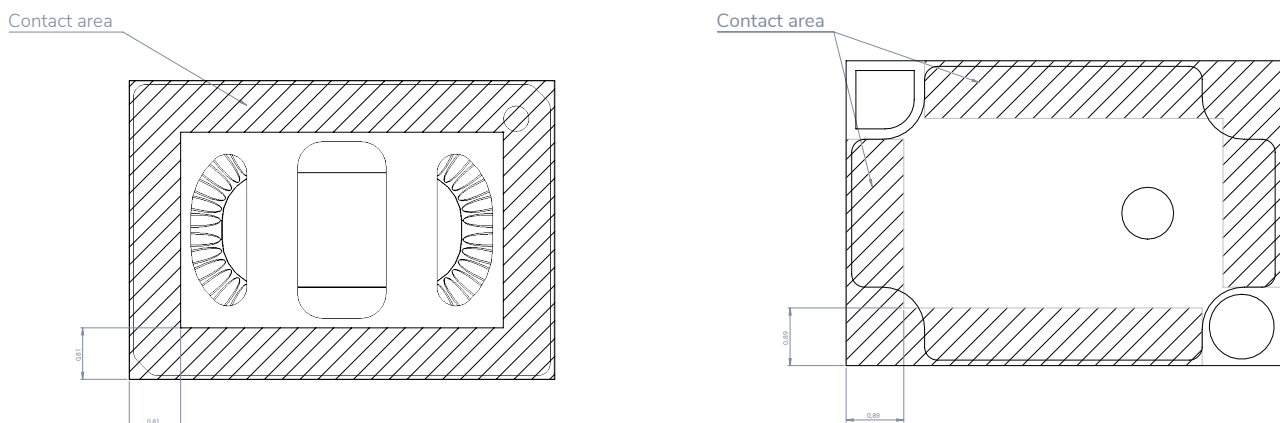


Figure 14: Recommended contact surfaces at back side (right) and front side (left) of MEMS speaker

CONNECTIVITY

The speaker is driven by applying voltage between the + and the - connection. The potential of + has to be always equal or higher than the -. To ensure this a DC voltage together with the AC signal has to be applied on +.

Attention: The AC peak voltage must always be smaller than or equal to the DC voltage.

The membrane will move downwards/inside by applying a positive voltage on the + connection.

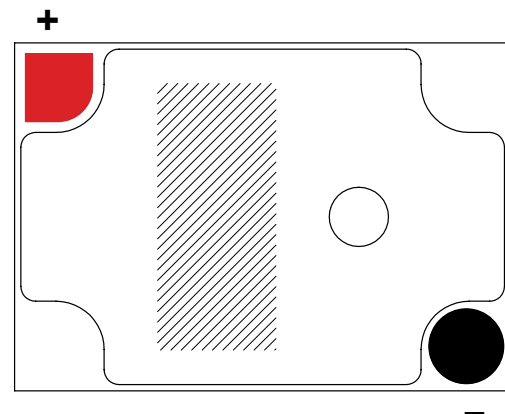


Figure 15: Electrical connections of the speaker back side

LABELLING

Each speaker is equipped with an 8 x 18 digital matrix code (DMC)

- DMC Size: 3.6 mm x 1.6 mm
- Pixel size: 0.2 mm
- Data format corresponds to the production date: NNYCCDSSSS. For example: 0191024022

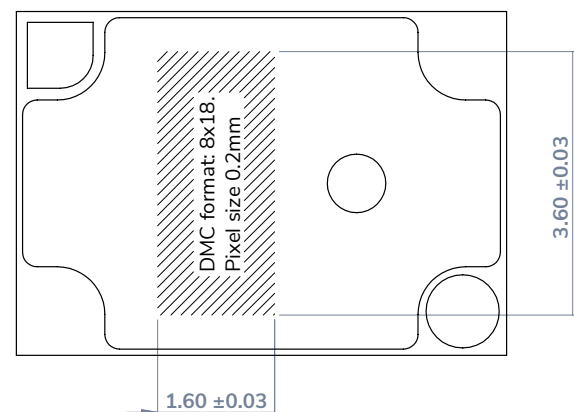


Figure 16: DMC at speaker backside

02	9	10	2	4022
NN	Y	CC	D	SSSS
Speaker type (01 = Adap; 02= Achelous)	Year (Last digit of the year)	Calendar week	Week day (First day starts on Sunday)	Serial number

PACKAGING

Thickness: 0.5 mm
QTY 150 PCS

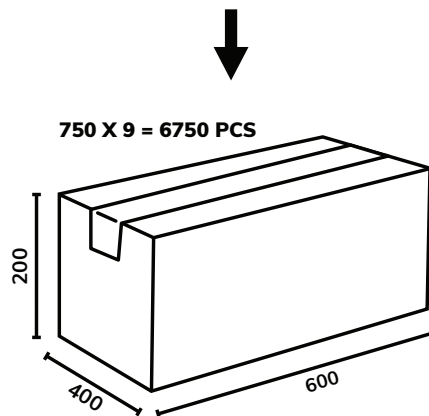
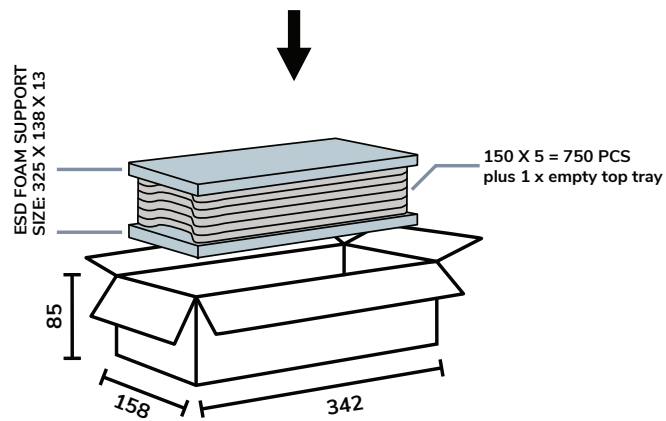
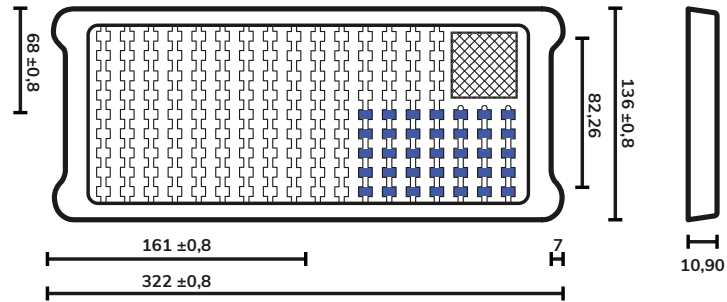


Figure 17: Packaging in tray and carton

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